

A cross-sectional view of a semiconductor device. It features a substrate 30 with a wavy interface. Above this interface is a layer 46, which contains several rectangular blocks 34. The top surface of the device is a flat layer 48. Arrows point from the labels 34, 46, 48, and 30 to their respective components.

A cross-sectional view of a semiconductor device. A substrate 54 is shown with a series of rectangular openings. A layer 50 is deposited over the substrate, filling the openings and forming a continuous top layer. The layer 50 is patterned into a series of rectangular blocks. The top surface of the layer 50 is indicated by reference numeral 52. The side surface of the layer 50 is indicated by reference numeral 50. The substrate 54 is indicated by reference numeral 54.

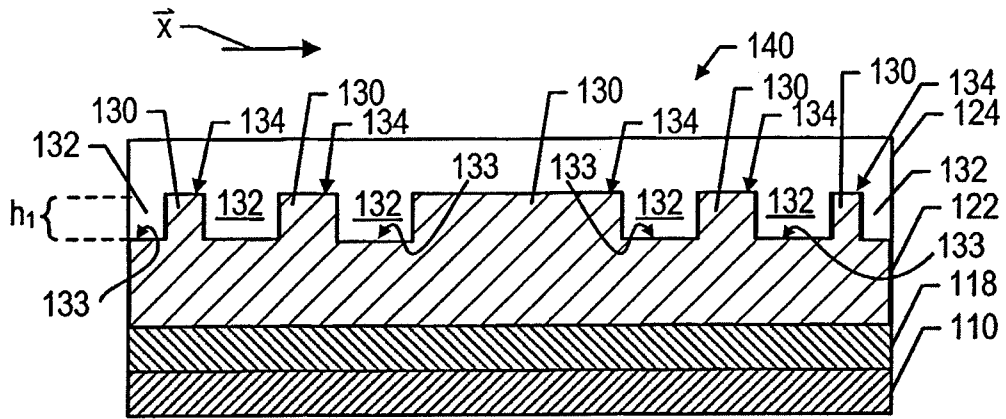


FIG. 4

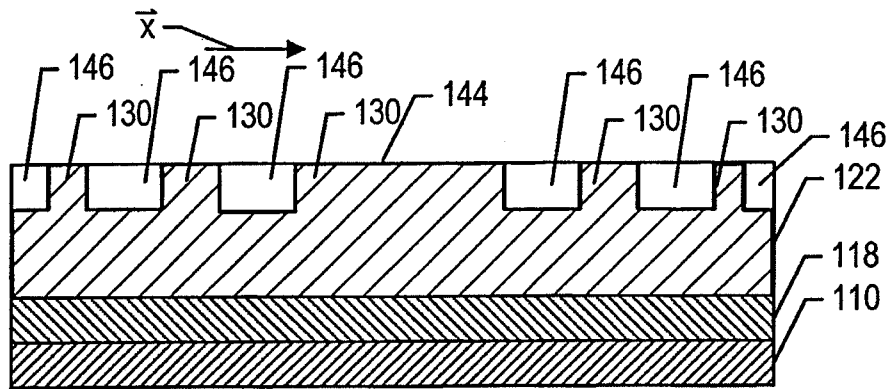


FIG. 5

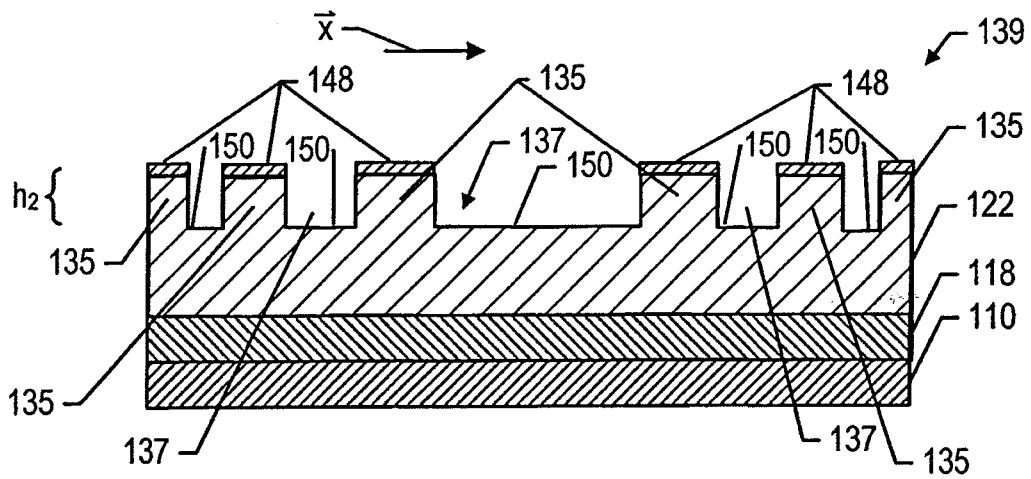


FIG. 6

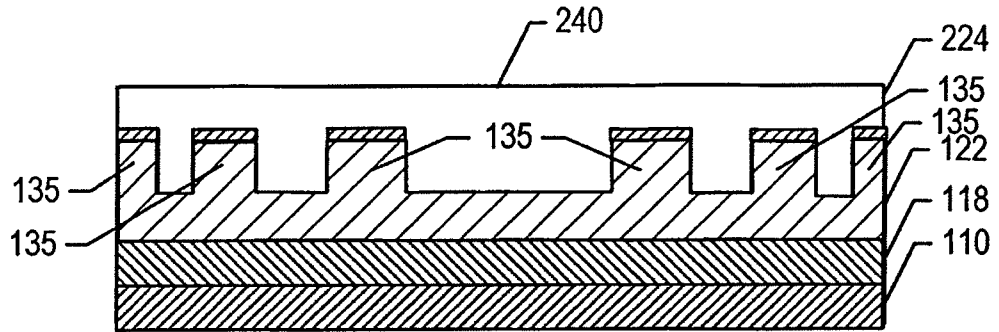


FIG. 7

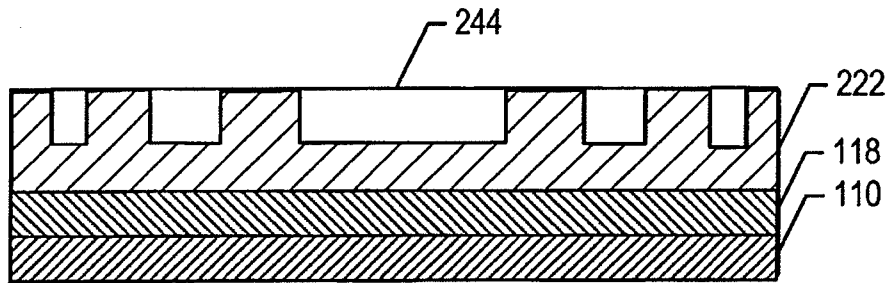


FIG. 8

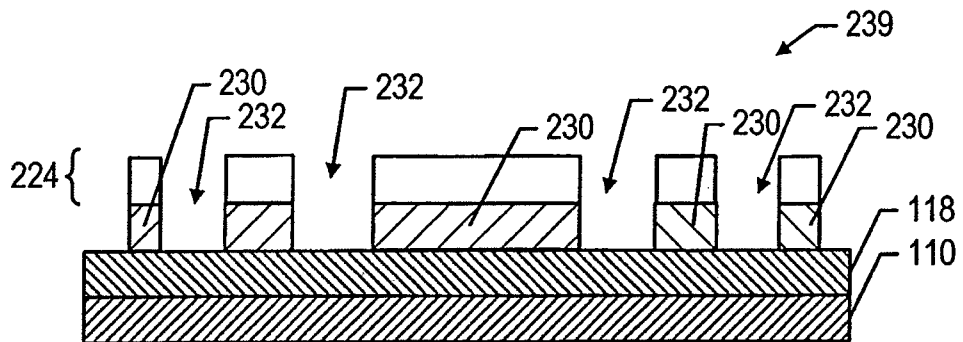


FIG. 9

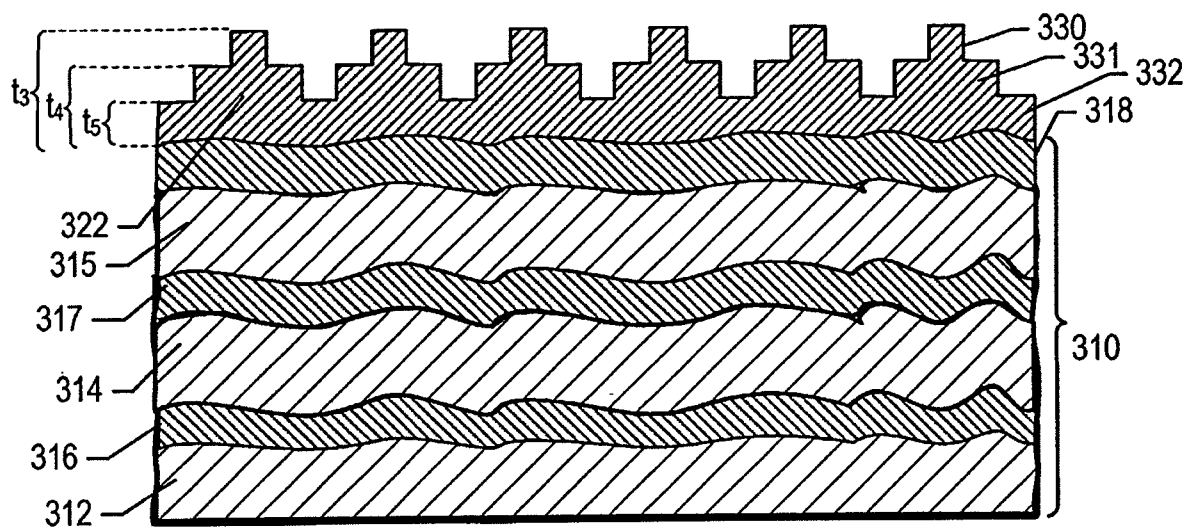


FIG. 10

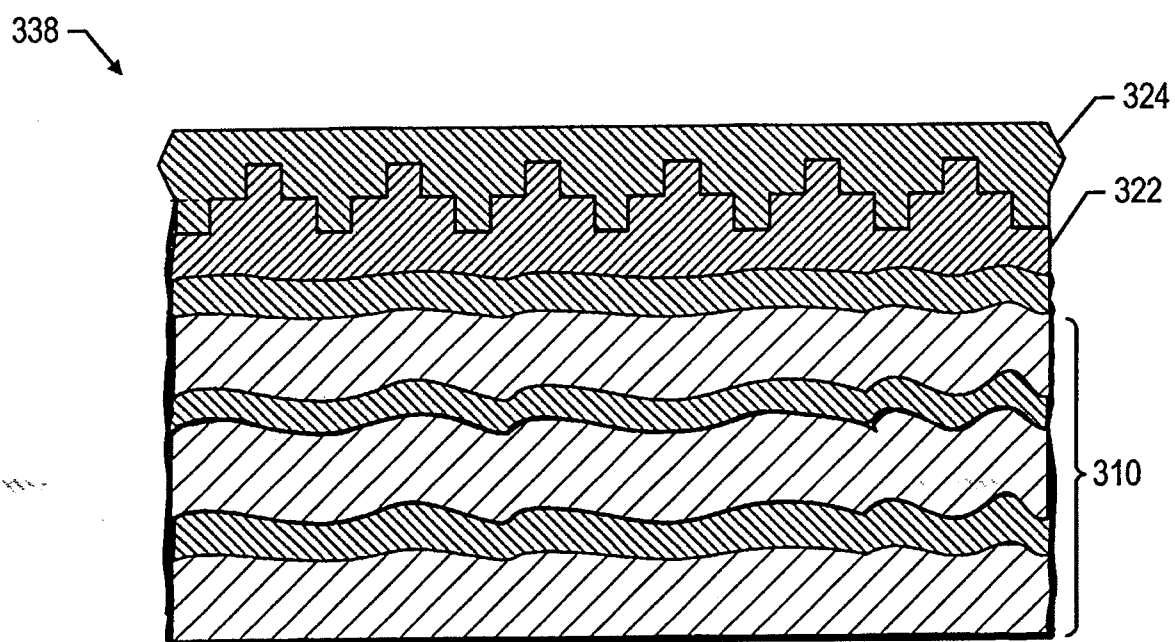


FIG. 11

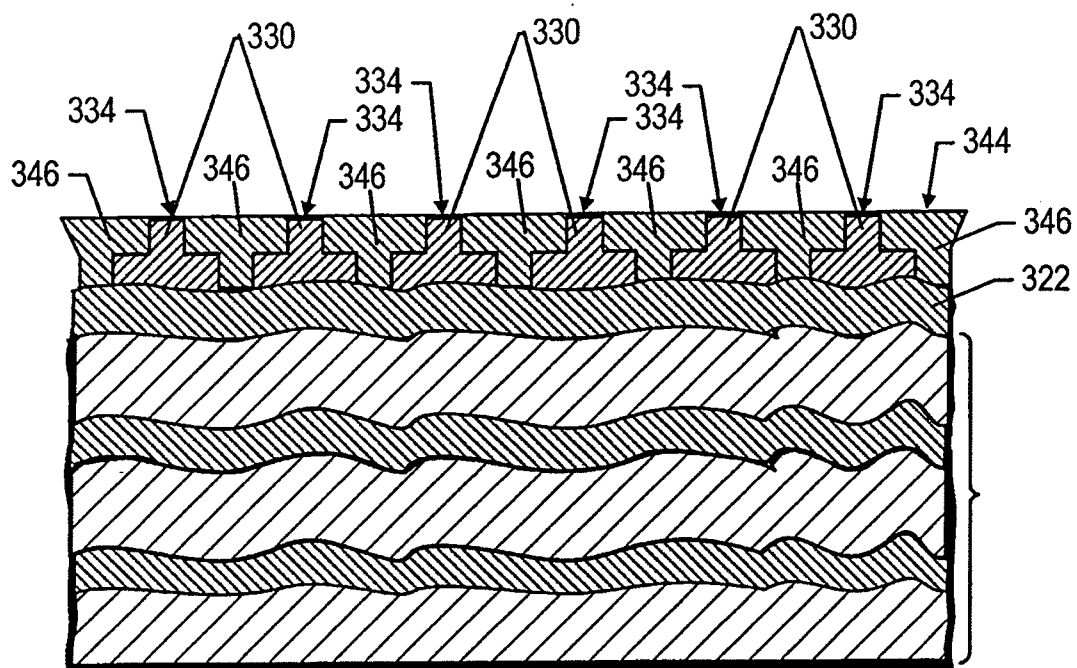


FIG. 12

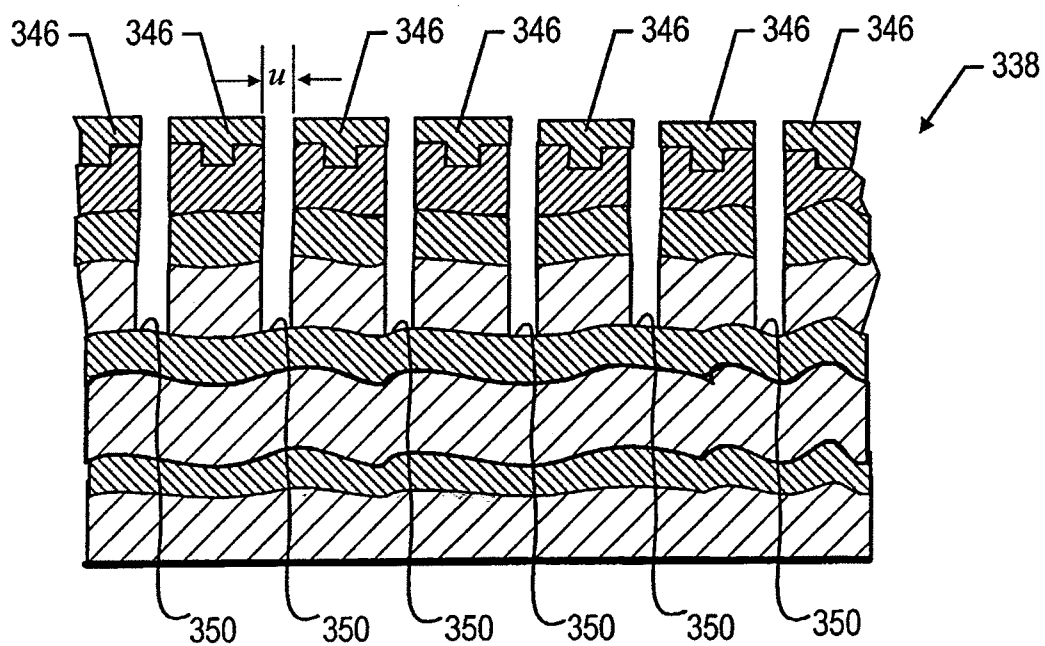


FIG. 13

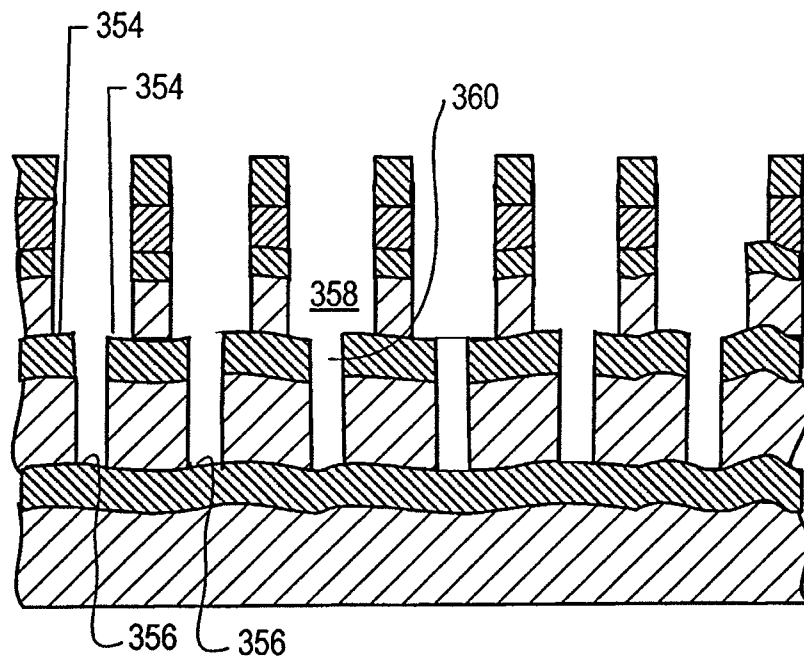


FIG. 14

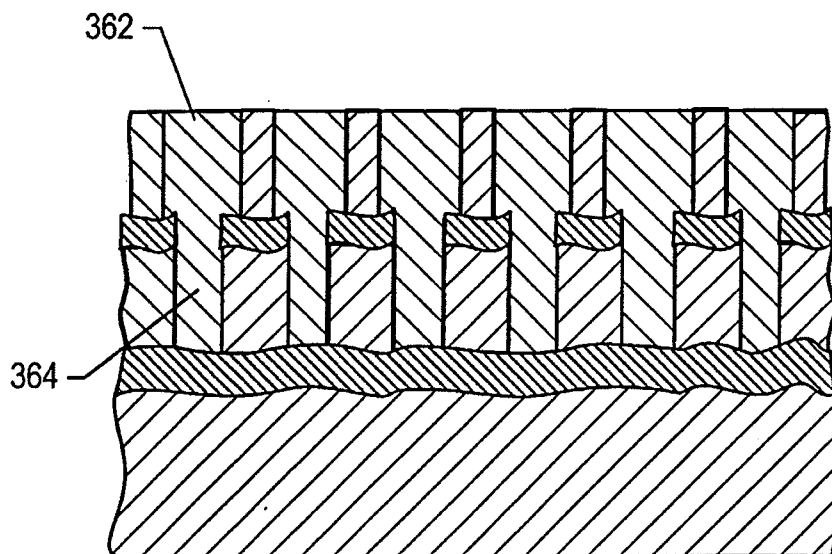


FIG. 15

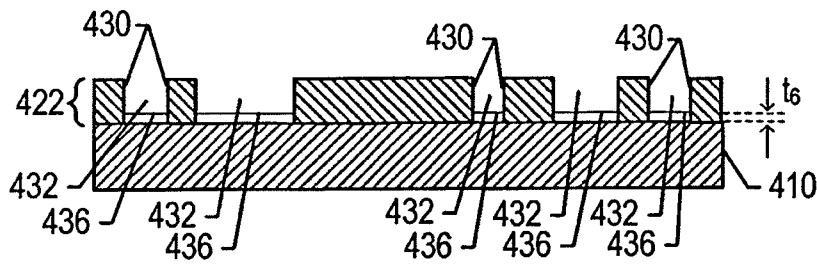


FIG. 16

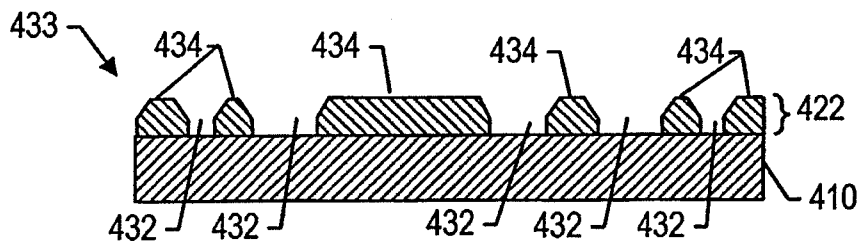


FIG. 17

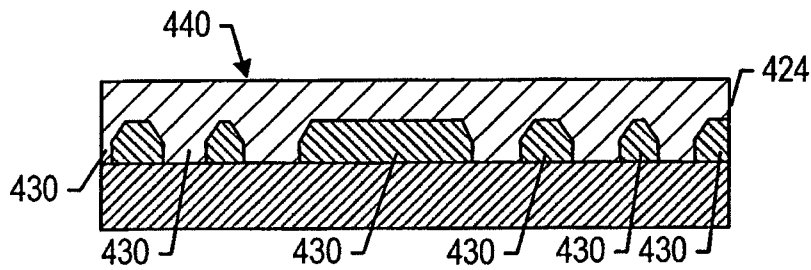


FIG. 18

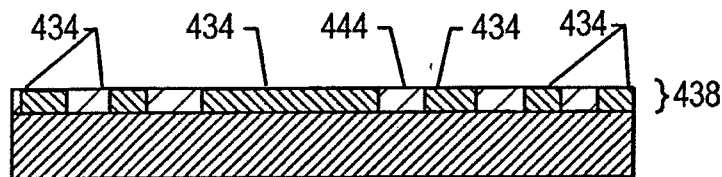


FIG. 19

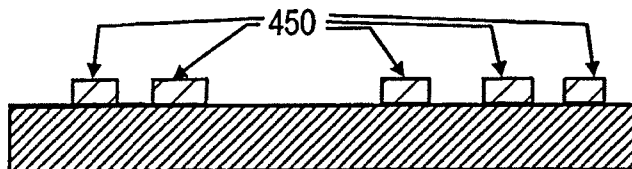


FIG. 20

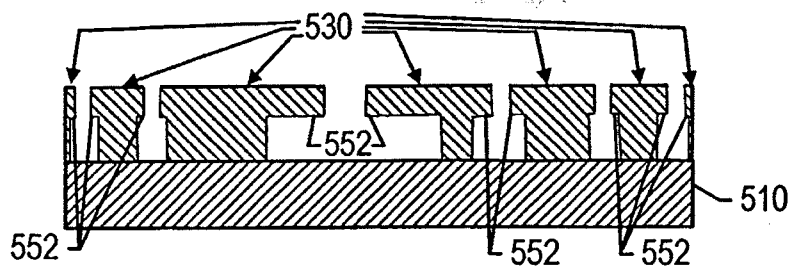


FIG. 21

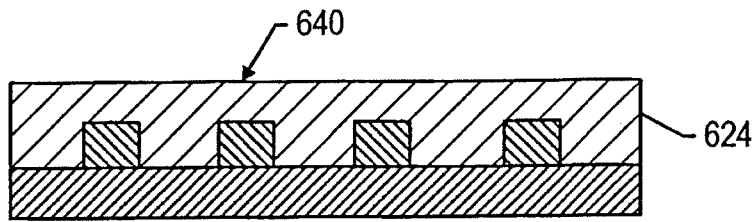


FIG. 22

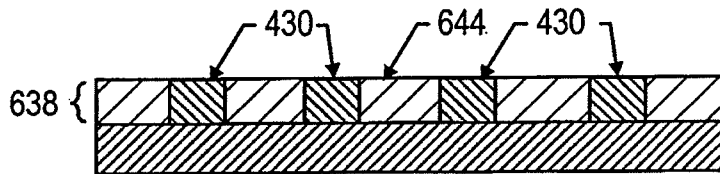


FIG. 23

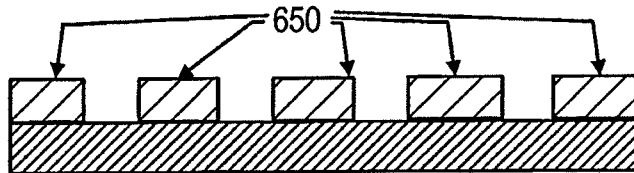


FIG. 24

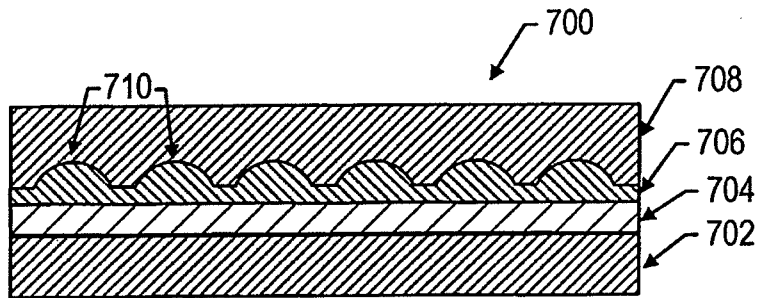


FIG. 25

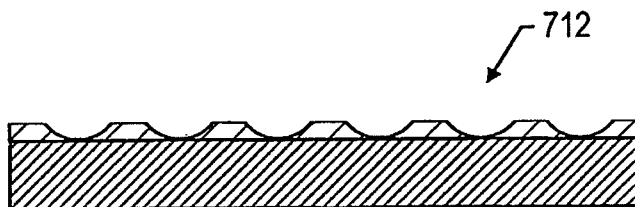


FIG. 26

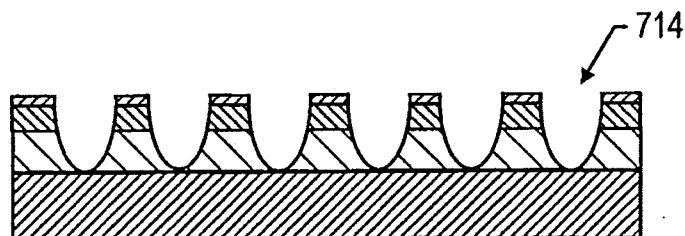


FIG. 27